

NCE N-Channel Super Trench III Power MOSFET

Description

The series of devices uses **Super Trench III** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(on)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

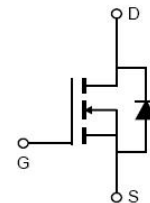
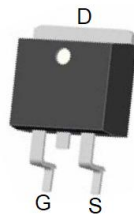
General Features

- $V_{DS} = 150V, I_D = 175A$
 $R_{DS(on)} = 3.6m\Omega$, typical @ $V_{GS} = 10V$
- Excellent gate charge x $R_{DS(on)}$ product(FOM)
- Very low on-resistance $R_{DS(on)}$
- 175 °C operating temperature
- Pb-free lead plating

100% UIS TESTED!

100% ΔV_{ds} TESTED!

TO-263-2L



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCEP048NH150D	NCEP048NH150D	TO-263-2L	-	-	-

Absolute Maximum Ratings ($T_c = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	150	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	175	A
Drain Current-Continuous($T_c = 100^\circ C$)	$I_D(100^\circ C)$	122	A
Pulsed Drain Current	I_{DM}	700	A
Maximum Power Dissipation	P_D	323	W
Derating factor		2.15	W/ $^\circ C$
Single pulse avalanche energy ^(Note 1)	E_{AS}	1536	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 175	$^\circ C$

Thermal Characteristic

Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.46	$^\circ C/W$
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Electrical Characteristics (T_c=25°C unless otherwise noted)

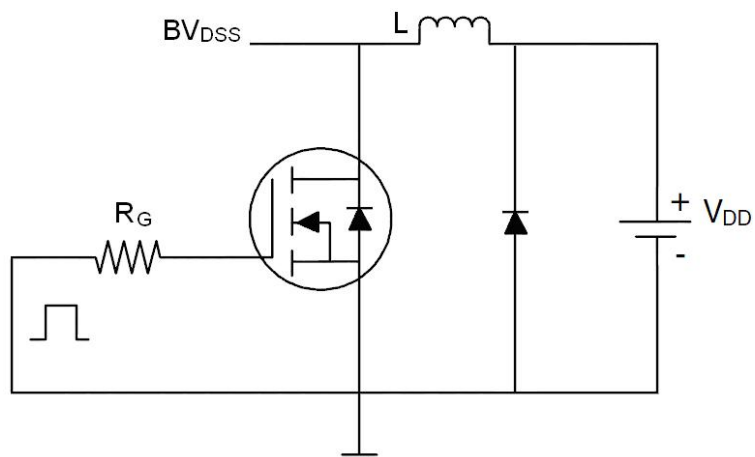
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	150	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =150V, V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
On Characteristics						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2.5	3.5	4.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =20A	-	3.6	4.8	mΩ
Forward Transconductance	g _{FS}	V _{DS} =10V, I _D =40A	-	75	-	S
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} =75V, V _{GS} =0V, F=1.0MHz	-	7150	-	PF
Output Capacitance	C _{oss}		-	2050	-	PF
Reverse Transfer Capacitance	C _{rss}		-	47	-	PF
Switching Characteristics (Note 2)						
Turn-on Delay Time	t _{d(on)}	V _{DD} =75V, I _D =75A V _{GS} =10V, R _G =4.7Ω	-	30	-	nS
Turn-on Rise Time	t _r		-	40	-	nS
Turn-Off Delay Time	t _{d(off)}		-	70	-	nS
Turn-Off Fall Time	t _f		-	15	-	nS
Total Gate Charge	Q _g	V _{DS} =75V, I _D =20A, V _{GS} =10V	-	106	-	nC
Gate-Source Charge	Q _{gs}		-	36	-	nC
Gate-Drain Charge	Q _{gd}		-	27	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _F = I _S	-	-	1.2	V
Diode Forward Current	I _S		-	-	175	A
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F = 100A	-	108	-	nS
Reverse Recovery Charge	Q _{rr}	di/dt = 100A/μs	-	270	-	nC

Notes:

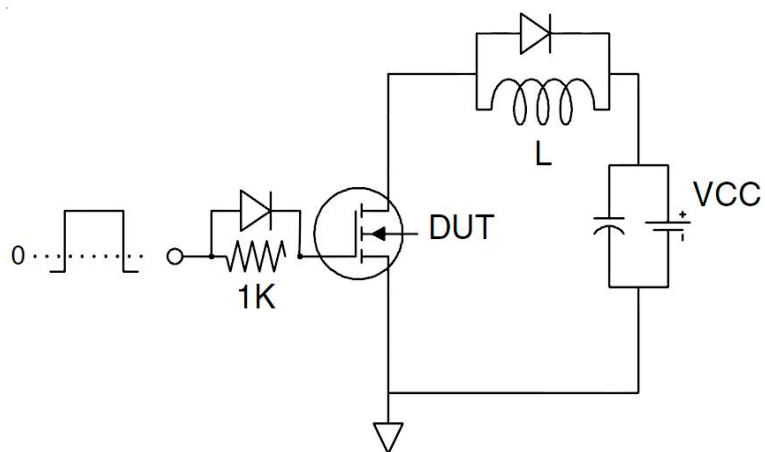
1. EAS condition : T_J=25°C, V_{DD}=50V, V_G=10V, L=0.5mH, R_G=25Ω
2. Guaranteed by design, not subject to production
3. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_J(MAX)=175°C. The SOA curve provides a single pulse rating.

Test Circuit

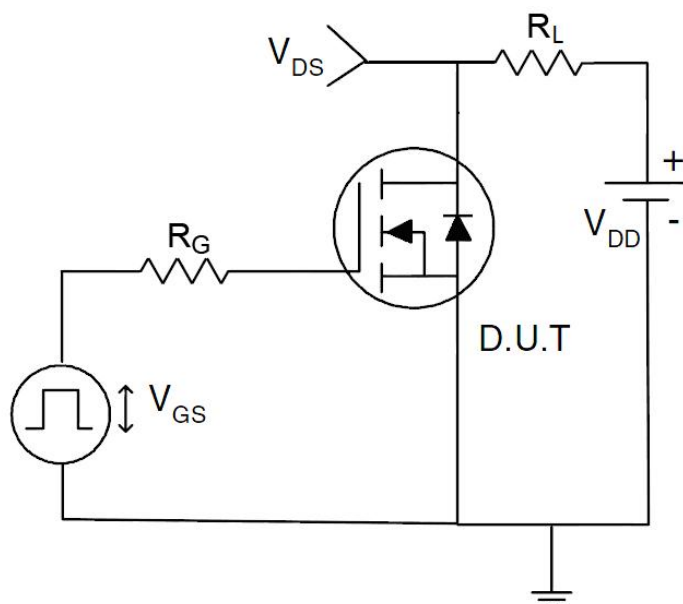
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit



Typical Electrical and Thermal Characteristics

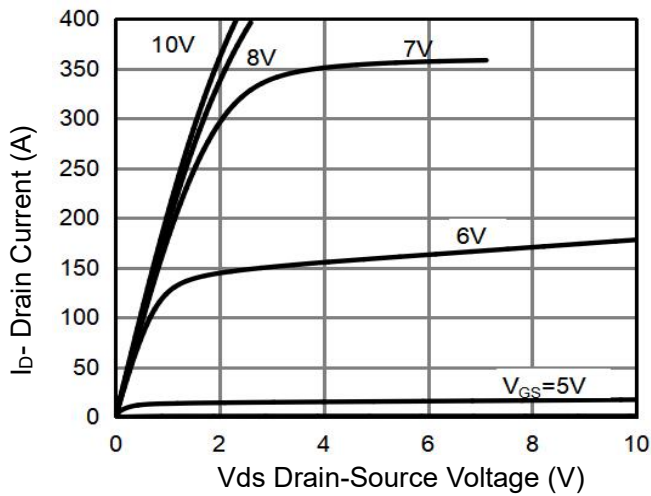


Figure 1 Output Characteristics

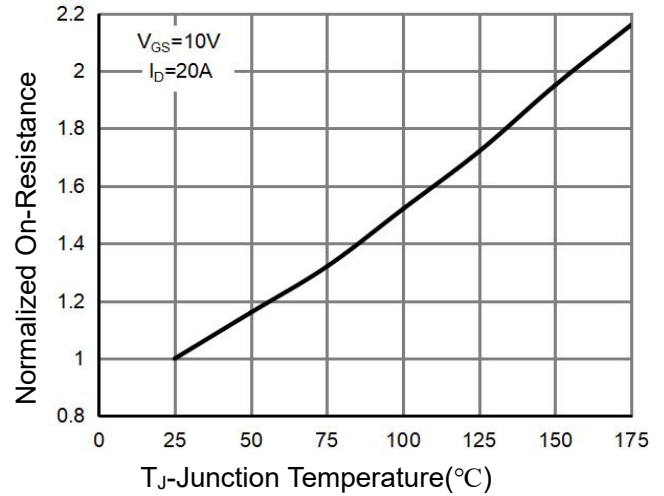


Figure 4 Rdson-Junction Temperature

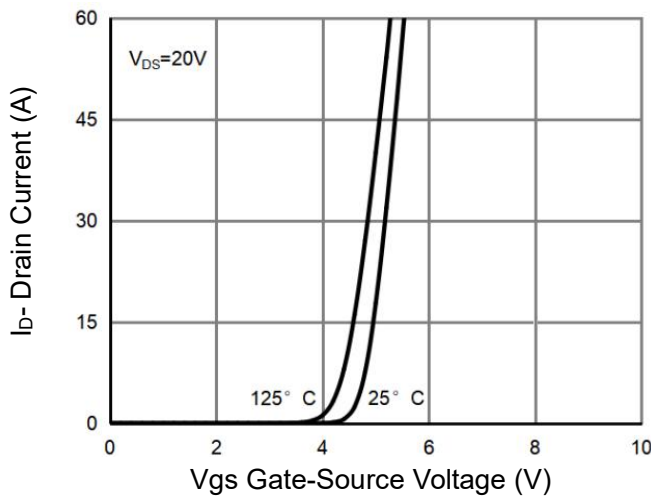


Figure 2 Transfer Characteristics

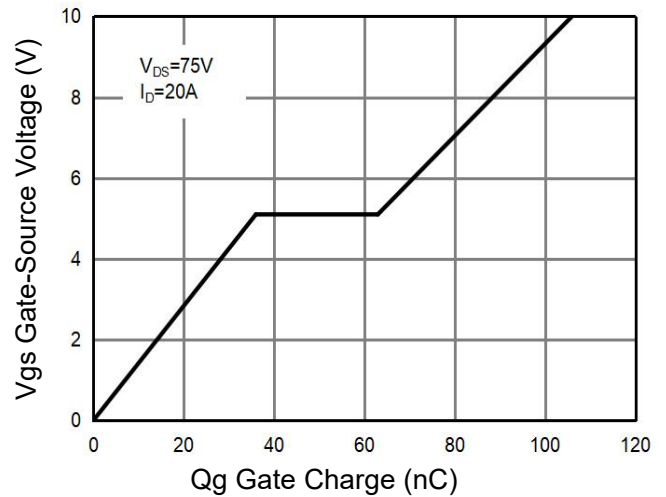


Figure 5 Gate Charge

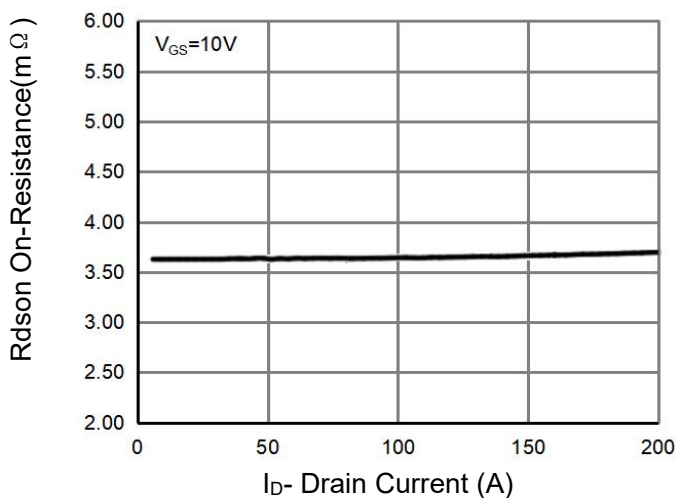


Figure 3 Rdson- Drain Current

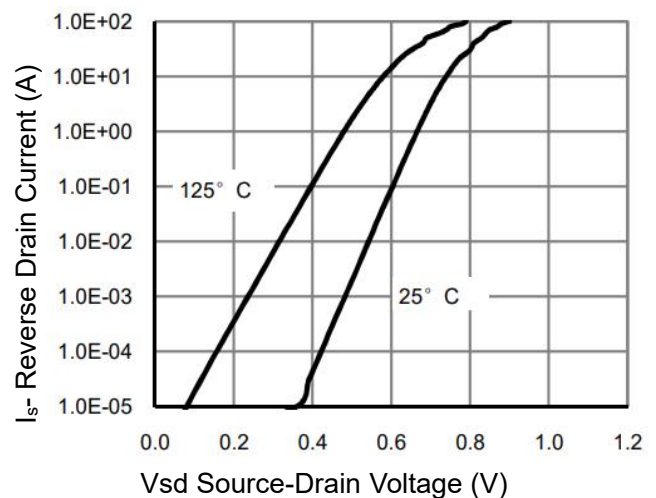


Figure 6 Source- Drain Diode Forward

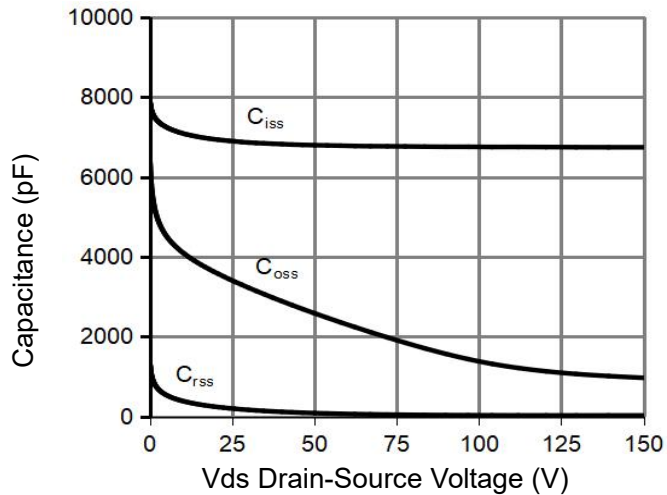


Figure 7 Capacitance vs Vds

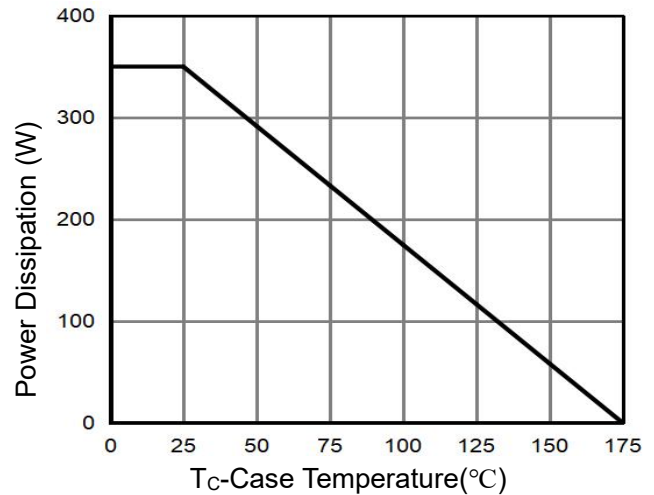


Figure 10 Power De-rating

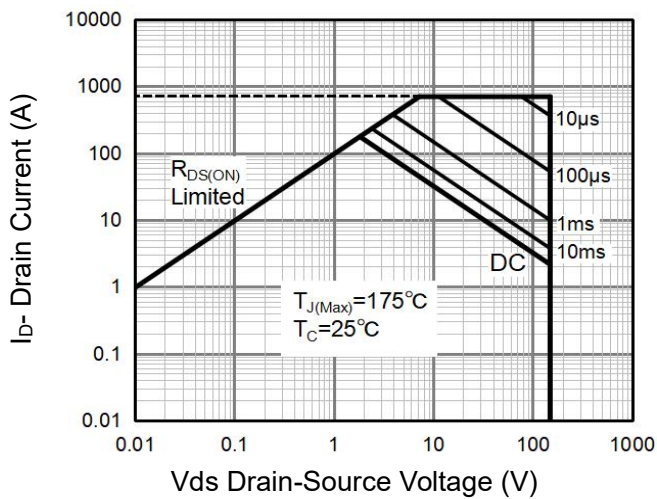


Figure 8 Safe Operation Area (Note3)

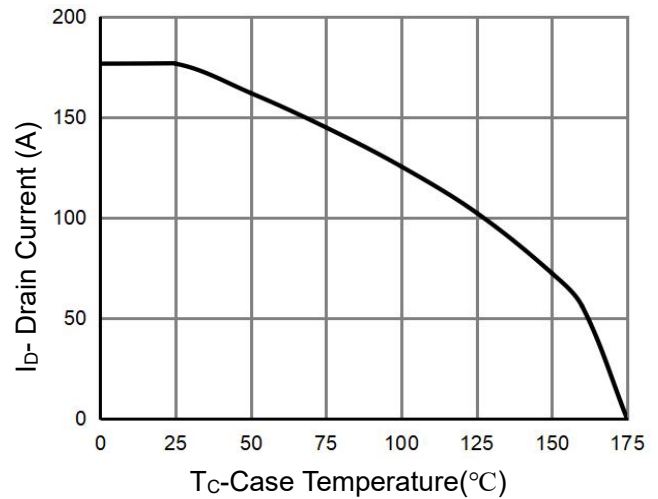


Figure 11 Current De-rating

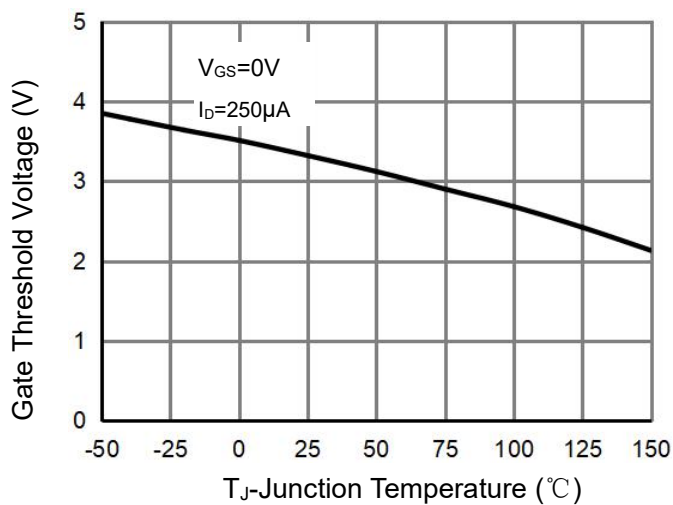


Figure 9 $V_{GS(th)}$ -Junction Temperature

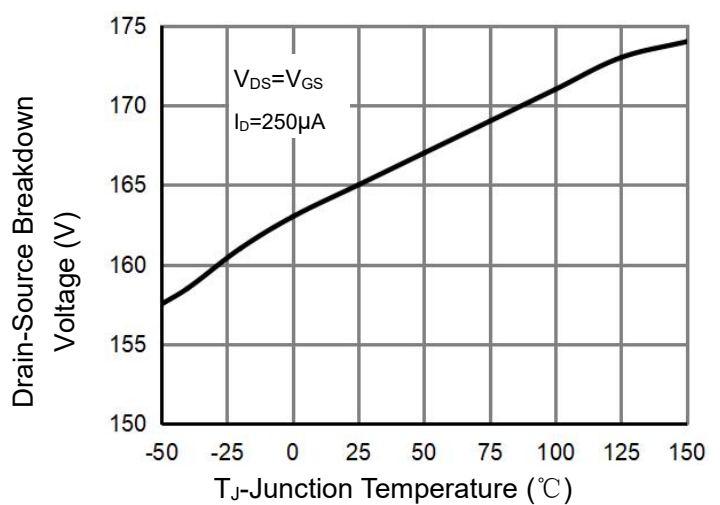


Figure 12 BV_{DSS} -Junction Temperature

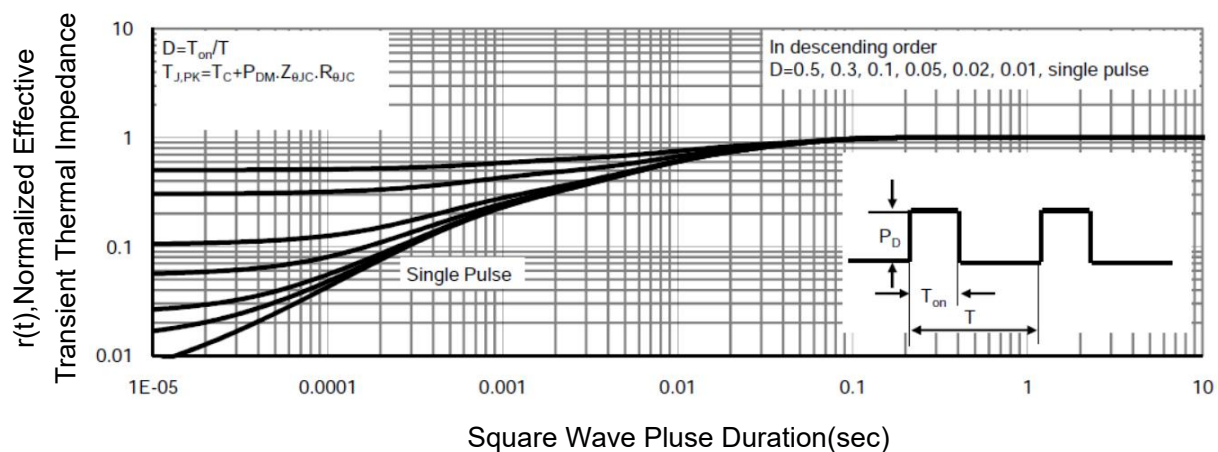
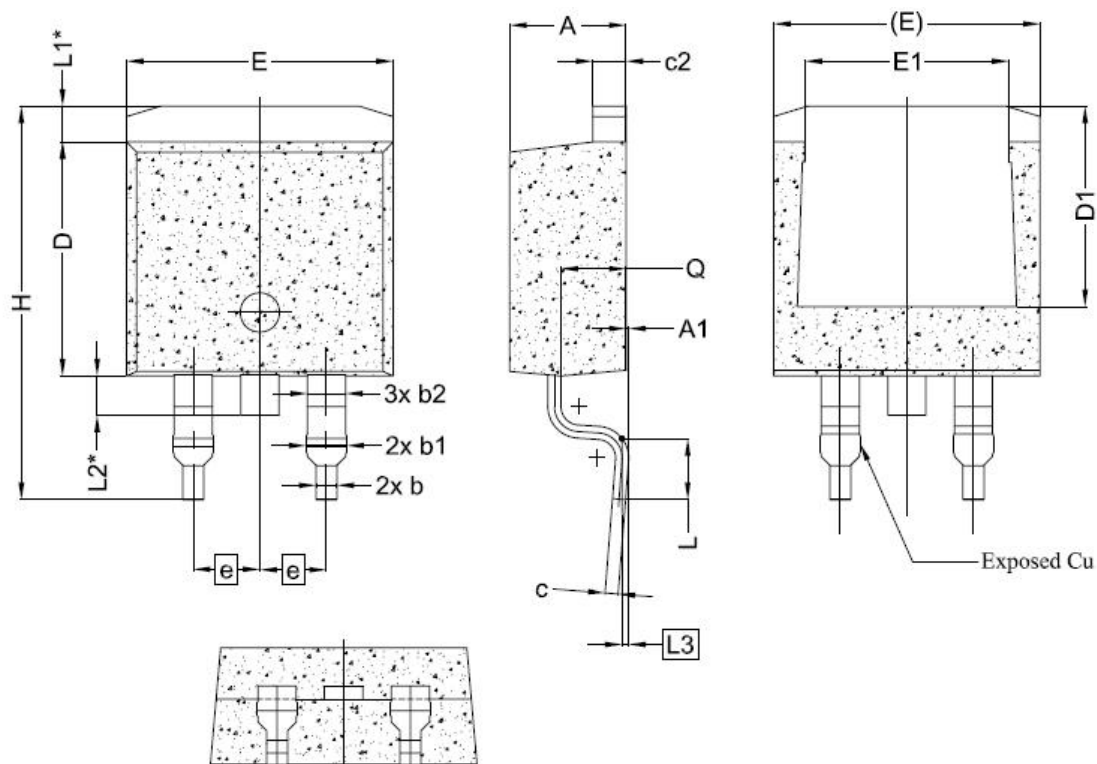


Figure 13 Normalized Maximum Transient Thermal Impedance

TO-263-2L Package Information



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	4.24	4.44	4.64
A1	0.00	0.10	0.15
b	0.70	0.80	0.90
b1	1.20	1.55	1.75
b2	1.20	1.45	1.70
c	0.40	0.50	0.60
c2	1.15	1.27	1.40
D	8.82	8.92	9.02
D1	6.86	7.65	—
E	9.96	10.16	10.36
E1	6.89	7.77	7.89
e	2.54 BSC		
H	14.61	15.00	15.88
L	1.78	2.32	2.79
L1	1.36 REF.		
L2	1.50 REF.		
L3	0.25 BSC		
Q	2.30	2.48	2.70

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